

Docket No.

AMEN	DMENT	TRANSM	ITTAL L	ETTER	M4065.	0014/P014 B
Application No. 09/940,791		Filing Date August 29, 2001		Examiner		Art Unit
				Kiesha L. Rose		2822
plicant(s): Larr	y D. Kinsman					
ention: LOW P	ROFILE BALL	GRID ARRAY	PACKAGE			
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	Remaining After	Number Previously	Number Extra Claims			
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Total Claims Independent	7	- 20 =		X		0.00
Claims	3	- 3 =		X		0.00
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Docket No.: M4065.0014/P014-B (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Larry D. Kinsman

Application No.: 09/940,791

Filed: August 29, 2001

For: LOW PROFILE BALL GRID ARRAY

PACKAGE

Group Art Unit: 2822

Examiner: Kiesha L. Rose

AMENDMENT

DX: Non-Fee Amenda.

Ommissioner for Patents
/ashington, DC 20231

Dear Sir:

This paper is in response to the Office Action of January 21, 2003, reject.

claims 39-45, please amend the above-identified U.S. patent application as follows:

IN THE CLAIMS:

20 42 and 45 as follows:

a central processing unit; and

a memory device connected to said central processing unit, said memory device comprised of a plurality of low profile ball grid array semiconductor packages, said low profile ball grid array semiconductor packages comprised of a base substrate having a top surface and a bottom surface, with an aperture therein which extends from said top surface to said bottom surface,

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